

Polyimide Film (TY6052E)



With the application of Bi-axial stretching technology, this brand polyimide film, the low thermal coefficient expansion polyimide film, is made from polyamic acid resins, which is obtained from a novel formula comprised of new anhydride monomers as well as a mine monomers, it not only processes the excellent performance of common polyimide film but also has better dimension stability, higher modulus of elasticity and lower thermal expansion coefficient.

1. Technical Requirements

performace Index

NO.	Index Description		Unit	Index Value	
				12.5μm	25.0μm
1	Tensile	CD/MD	Mpa	≥200	
2	Elongation	CD/MD	%	≥40	
3	Tensile modulus	CD/MD	GPa	≥4.0	
4	Heate expansion coefficient Longitudinal/Transverse200℃, 2h		%	≥0.1	
5	Electrical operating Frequency intensity	Average	MV/m	≥200	≥200
6	Heate expansion coefficient 25-200℃		ppm/℃	15-25	
7	A sexual 100%RH		%	≤2.5	
8	Volume resistivity 200℃		Ω cm	≥1.0x10 ¹²	
9	Relative dielectric Constant, 48-62Hz		-	3.0-3.5	
10	Dielectric Loss Factor 48-62Hz		-	≤0.002	

2. Application

6052E low thermal coefficient expansion polyimide film has higher dimension stability. Its CTE is very near copper foil which is ideal material for FPC as copper board cover.